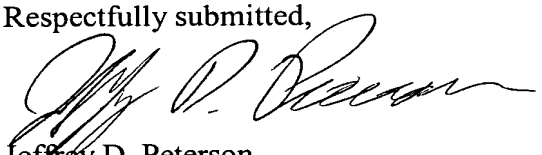
REMARKS

With the entry of the above amendments, 1, 3-8 and 10-15 are pending. Claim 1 was amended to include the chemical formula which was inadvertently deleted in the first preliminary amendment. Basis for this amendment can be found in the originally filed claim 1. Claims 1 and 2 were amended to remover the term "phosphorous" as the phosphorous containing structures have been removed from the claim. Applicants submit that no new matter was added by these amendments. Applicants respectfully submit that all of the pending claims are in condition for allowance.

Should the Examiner feel that any other point requires consideration or that the form of the claims can be improved, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted,



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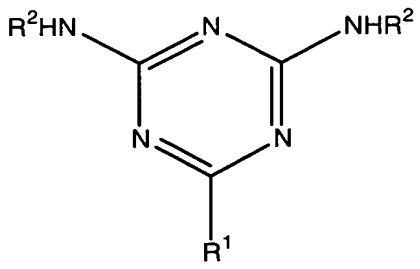
Listing of Claims

1. (Currently Amended) A ~~phosphorus- and~~ nitrogen-containing resin hardener, which has a structure represented by the following formula:



wherein R^2 represents a hydrogen atom and R^1 represents NHR^2, $C_{1\text{-}6}$alkyl or phenyl.

2. Cancelled

3. (Currently Amended) A flame retarding resin composition, which comprises (A) an epoxy resin, (B) the ~~phosphorus- and~~ nitrogen-containing resin hardener according to claim 1 and (C) a hardening promoter.

4. (Original) The flame retarding resin composition according to claim 3, wherein said epoxy resin is selected from the group consisting of glycidyl ethers of bisphenols, glycidyl ethers of biphenols, glycidyl ethers of dihydroxybenzenes, glycidyl ethers of nitrogen-containing hetero rings, glycidyl ethers of dihydroxynaphthalene, polyglycidyl ethers of phenolics and polyglycidyl ethers of polyhydric phenols.

5. (Original) The flame retarding resin composition according to claim 3, wherein said hardening promoter is selected from the group consisting of tertiary amines, tertiary

phosphines, quaternary ammonium salts, quaternary phosphonium salts, boric trifluoride complexs, lithium compounds and imidazole compounds.

6. (Original) The flame retarding resin composition according to claim 3, wherein the amount of the component (B) hardeners is 20 to 140% of the equivalent weight of the reactive hydrogen in said hardeners, when the epoxy equivalent weight of the component (A) epoxy resin is taken as 100%.

7. (Original) The flame retarding resin composition according to claim 3, wherein the amount of the component (C) hardening promoters is from 50 to 50,000ppm, based on the total weight of said flame retarding resin composition.

8. (Original) The flame retarding resin composition according to claim 3, which further comprises other hardeners selected from the group consisting of amines, bisphenolic resin, dihydroxybenzenes, polyhydric phenolic resin and phenolics.

9. Cancelled

10. (Previously Presented) A prepreg made of a flame retarding resin composition according to claim 3.

11. (Previously Presented) A composite made of a flame retarding resin composition according to claim 3.

12. (Previously Presented) A laminate made of a flame retarding resin composition according to claim 3.

13. (Previously Presented) A printed circuit board made of a flame retarding resin composition according to claim 3.

14. (Previously Presented) The flame retarding resin composition according to claim 3, wherein the composition is a substrate for build-up resin coated copper.

15. (Previously Presented) The flame retarding resin composition according to claim 3, wherein the composition is an epoxy molding compound.